



SSC8522GSG

Dual N-Channel Enhancement Mode MOSFET

➤ Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	I _D
20V	±12V	210mΩ@4.5V	0.9A
		240mΩ@2.5V	
		290mΩ@1.8V	

➤ Description

This device is N-Channel enhancement MOSFET. Uses Trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

➤ Applications

- Motor Drive Control
- Portable Devices
- DCDC Conversion
- Power Supplies

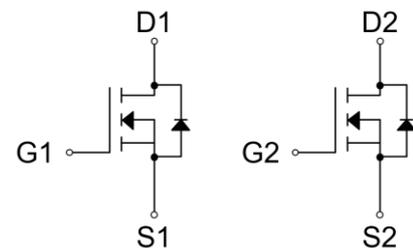
➤ Ordering Information

Device	Package	Shipping
SSC8522GSG	SOT-363	3000/Reel

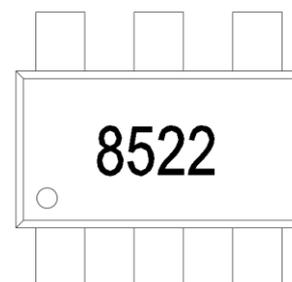
➤ Pin Configuration



SOT-363 (Top View)



Pin Configuration



Markin



➤ **Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit	
V_{DSS}	Drain-to-Source Voltage	20	V	
V_{GSS}	Gate-to-Source Voltage	± 12	V	
I_D	Continuous Drain Current ^a	$T_A=25^\circ\text{C}$	0.9	A
		$T_A=100^\circ\text{C}$	0.5	
I_{DM}	Pulsed Drain Current ^b	3.6	A	
P_D	Power Dissipation ^a	$T_A=25^\circ\text{C}$	0.27	W
		$T_A=100^\circ\text{C}$	0.11	
T_J	Operation junction temperature	-55~150	$^\circ\text{C}$	
T_{STG}	Storage temperature range	-55~150		

➤ **Thermal Resistance Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	459	$^\circ\text{C}/\text{W}$

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.

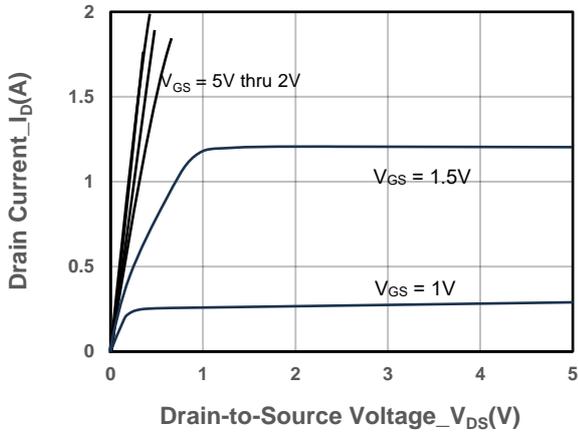


➤ **Electrical Characteristics (T_A=25°C unless otherwise noted)**

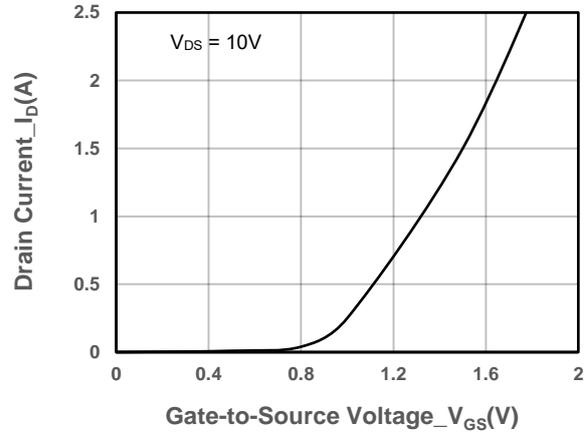
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.35	0.65	1	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 0.5A		210	380	mΩ
		V _{GS} = 2.5V, I _D = 0.5A		240	450	mΩ
		V _{GS} = 1.8V, I _D = 0.35A		290	800	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±10	uA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 0.15A			1.2	V
Input Capacitance	C _{ISS}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz		63		pF
Output Capacitance	C _{OSS}			37		
Reverse Transfer Capacitance	C _{RSS}			22		
Total Gate Charge	Q _G	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 0.5A		1.3		nC
Gate to Source Charge	Q _{GS}			0.28		
Gate to Drain Charge	Q _{GD}			0.23		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 0.5A, R _G = 6Ω		4.1		ns
Rise Time	T _r			2.7		
Turn-off Delay Time	T _{D(OFF)}			13.4		
Fall Time	T _f			5.5		
Diode Recovery Time	T _{rr}	I _F =0.5A, di/dt=100A/us		14		ns
Diode Recovery Charge	Q _{rr}	I _F =0.5A, di/dt=100A/us		10		nC



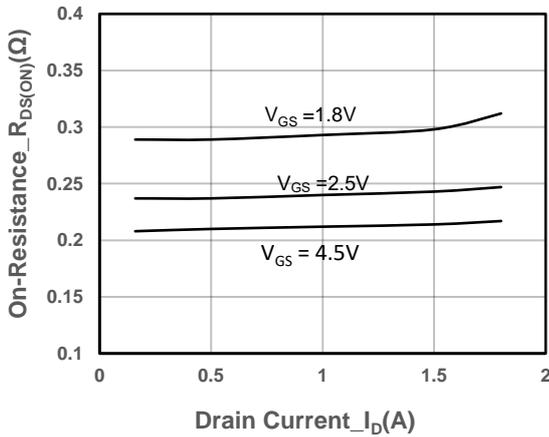
➤ **Typical Performance Characteristics (T_A=25°C unless otherwise noted)**



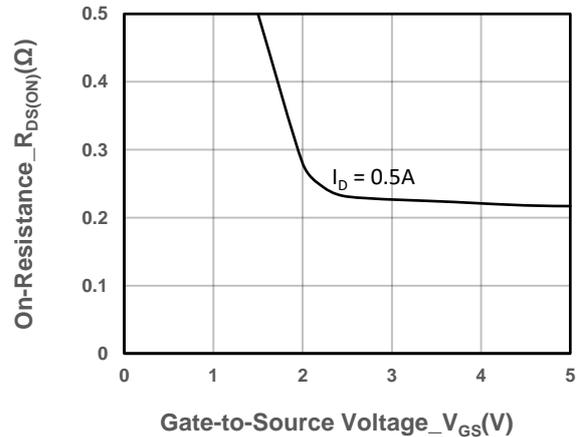
Output Characteristics



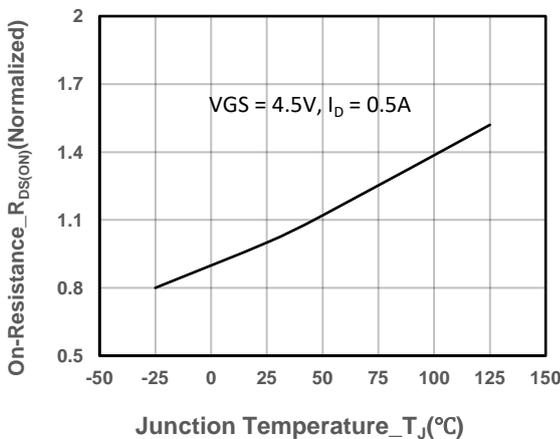
Transfer Characteristics



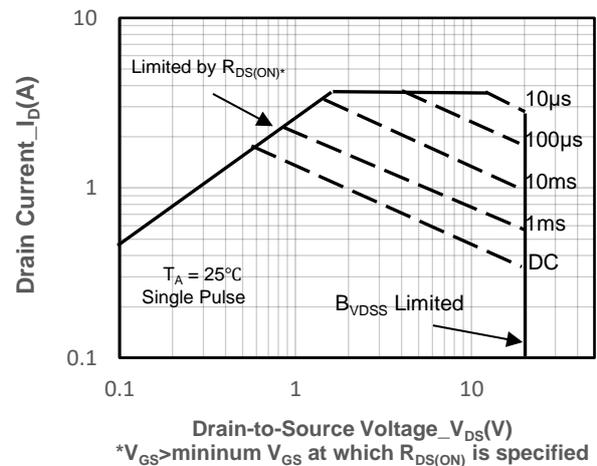
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



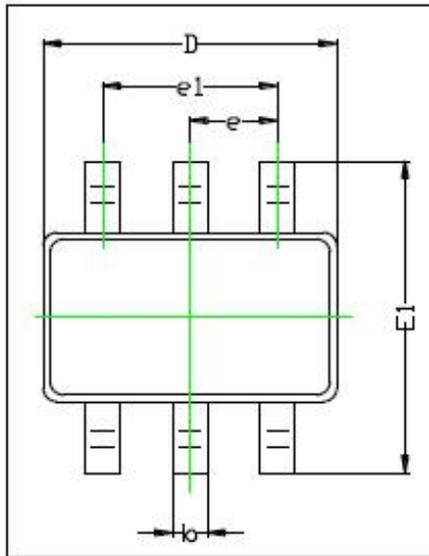
On-Resistance vs. Junction Temperature



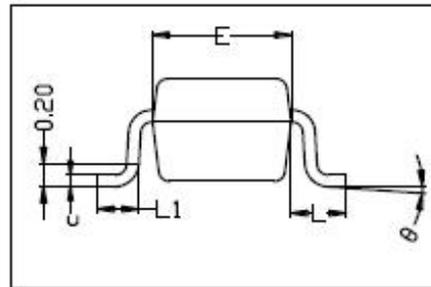
Safe Operating Area vs. Junction-to-Ambient

➤ Package Information

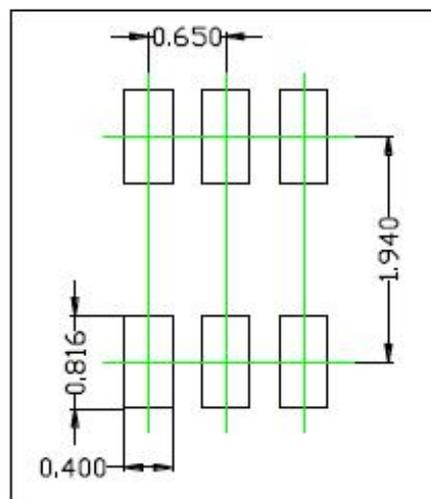
TOP VIEW



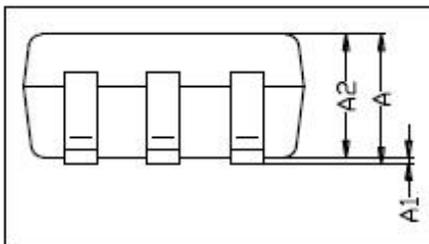
SIDE VIEW



SOLDERING PATTERN



FRONT VIEW



SYMBOL	DIMENSIONS IN MILLIMETER	
	MIN	MAX
A	0.900	1.000
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.300
c	0.100	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.400
e	0.650 TYP.	
e1	1.200	1.400
L	0.525 REF.	
L1	0.260	0.450
θ	0°	8°



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